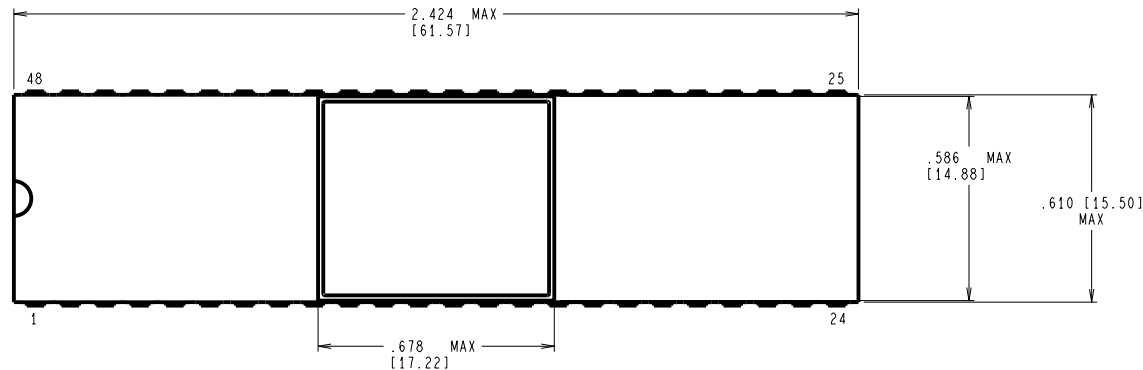
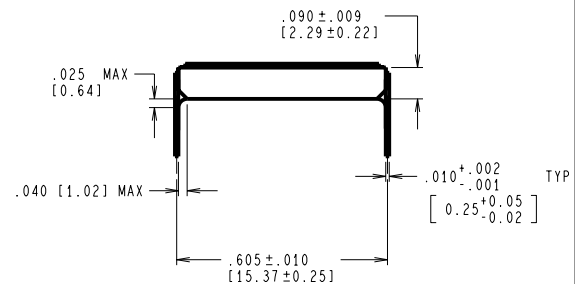


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW PER NEW STANDARD.	10241	02/16/94	DEG/TP
F	.085 MAX WAS .080 ± .008; .610 MAX WAS .595 ± .006.	10478	07/01/94	DEG/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - a. 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - b. 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
3. DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
4. REFERENCE JEDEC REGISTRATION MS-015, VARIATION CF, DATED 7/90.

**MIL-M-38510
CONFIGURATION CONTROL**

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN	Dwayne Grady	02/16/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DTG. CHK.			DIP, SIDEBRAZED CERAMIC, 48 LEAD			
ENGR. CHK.						
APPROVAL						
			SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]			N/A	C	MKT-D48A	F
DO NOT SCALE DRAWING					SHEET 1 of 1	